MSKSEMI 美森科













ESD

VS

TSS

MOV

GDT

PLED

USBLC6-2P6-MS

Product specification





Features

Ultra low leakage: nA level

Operating voltage: 5V

Low clamping voltage

• Complies with following standards:

- IEC 61000-4-2 (ESD) immunity test

Air discharge: ±15kV

Contact discharge: ±8kV

- IEC61000-4-4 (EFT) 40A (5/50ns)

RoHS Complian

Mechanical Characteristics

Package: SOT-666

• Lead Finish: Lead Free

• UL Flammability Classification Rating 94V-0

Quantity Per Reel:3,000pcs

Reel Size:7inch

Applications

USB 2.0 power and data line

Set-top box and digital TV

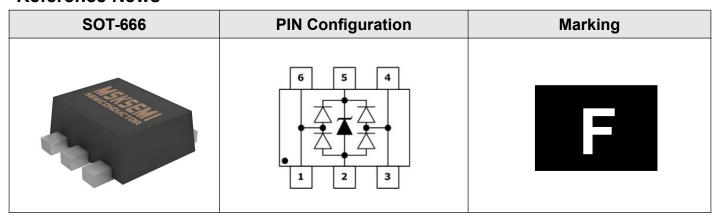
• Digital video interface (DVI)

Notebook Computers

SIM Ports

• 10/100 Ethernet

Reference News



Absolute Maximum Ratings(Tamb=25°C unless otherwise specified)

| Parameter | Symbol | Value | Unit |
|---------------------------------|------------------|-------------|------------|
| Peak Pulse Power (8/20µs) | Ррр | 120 | W |
| ESD per IEC 61000-4-2 (Air) | V _{ESD} | ±15 | Kv |
| ESD per IEC 61000-4-2 (Contact) | | ±8 | |
| Operating Temperature Range | TJ | -55 to +125 | °C |
| Storage Temperature Range | Тѕтл | -55 to +150 | $^{\circ}$ |



Electrical Characteristics (TA=25°C unless otherwise specified)

| Part Number | Vous (\) | V (V) | H- | V c | V | C | l _R µA | C (Pf) |
|---------------|-----------------|---------|------|------------|-------|------|----------------------|-----------|
| Part Number | VRWM (V) VBR (V | VBR (V) | (mA) | @1A | (Max) | (@A) | (Max) | (Typ.) |
| USBLC6-2P6-MS | 5 | 6 | 1 | 13 | 30 | 4 | 1 | 0.9 |

Characteristic Curves

Fig1. 8/20 µs Pulse Waveform

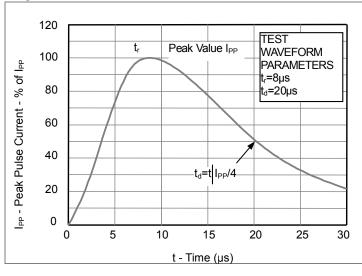


Fig2. ESD Pulse Waveform (according to IEC 61000-4-2)

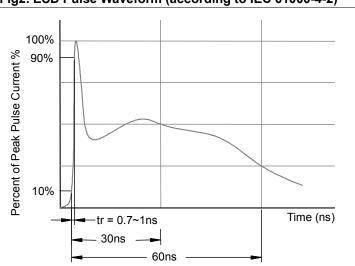
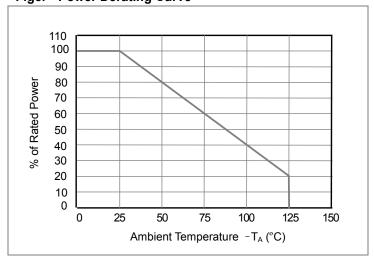
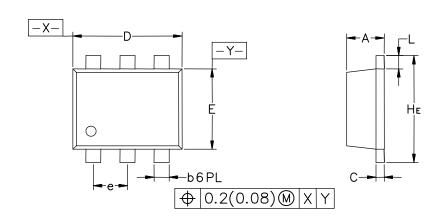


Fig3. Power Derating Curve



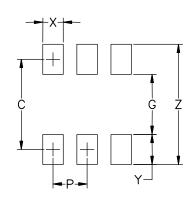


SOT-666 Package Outline & Dimensions



| Cumbal | | Inches | | Millimeters | | | |
|--------|----------|--------|-------|-------------|------|------|--|
| Symbol | Min. | Nom. | Max. | Min. | Nom. | Max. | |
| Α | 0.020 | 0.021 | 0.023 | 0.50 | 0.55 | 0.60 | |
| b | 0.007 | 0.009 | 0.011 | 0.17 | 0.22 | 0.27 | |
| С | 0.003 | 0.005 | 0.007 | 0.08 | 0.12 | 0.18 | |
| D | 0.059 | 0.062 | 0.066 | 1.50 | 1.60 | 1.70 | |
| E | 0.043 | 0.047 | 0.051 | 1.10 | 1.20 | 1.30 | |
| е | 0.02 BSC | | | 0.5 BSC | | | |
| L | 0.004 | 0.008 | 0.012 | 0.10 | 0.20 | 0.30 | |
| HE | 0.059 | 0.062 | 0.067 | 1.50 | 1.60 | 1.70 | |

Soldering Footprint



| Symbol | Inches | Millimeters |
|--------|--------|-------------|
| С | 0.0531 | 1.35 |
| G | 0.0354 | 0.90 |
| Р | 0.0197 | 0.50 |
| Х | 0.0118 | 0.30 |
| Y | 0.0177 | 0.45 |
| Z | 0.0709 | 1.80 |

Order information

| Orderable Device | Package | Packing Option |
|------------------|---------|----------------|
| USBLC6-2P6-MS | SOT-666 | 3000PCS |



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